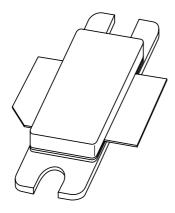
DISCRETE SEMICONDUCTORS

DATA SHEET



BLF1820-70UHF power LDMOS transistor

Product specification Supersedes data of 2001 Feb 12 2003 Feb 10





UHF power LDMOS transistor

BLF1820-70

FEATURES

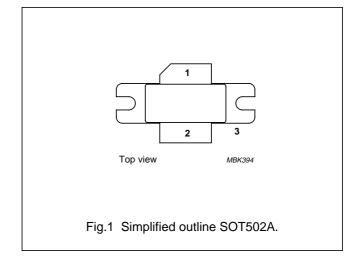
- Typical 2-tone performance at a supply voltage of 26 V and I_{DQ} of 500 mA:
 - Output power = 65 W (PEP)
 - Gain = 12 dB
 - Efficiency = 32%
 - dim = -26 dBc
- · Easy power control
- · Excellent ruggedness
- · High power gain
- · Excellent thermal stability
- Designed for broadband operation (1800 to 2000 MHz)
- · Internally matched for ease of use.

APPLICATIONS

 RF power amplifiers for GSM, EDGE and CDMA base stations and multicarrier applications in the 1800 to 2000 MHz frequency range.

PINNING

PIN	DESCRIPTION				
1	drain				
2	gate				
3	source, connected to flange				



DESCRIPTION

70 W LDMOS power transistor for base station applications at frequencies from 1800 to 2000 MHz.

QUICK REFERENCE DATA

RF performance at $T_h = 25$ °C in a common source test circuit.

MODE OF OPERATION	f	V _{DS}	P _L	G _p	η _D	d _{im}
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
2-tone, class-AB	$f_1 = 2000; f_2 = 2000.1$	26	65 (PEP)	>11	>30	≤–25

CAUTION

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling. For further information, refer to Philips specs.: SNW-EQ-608, SNW-FQ-302A and SNW-FQ-302B.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _{DS}	drain-source voltage	_	65	٧
V_{GS}	gate-source voltage	_	±15	٧
I _D	DC drain current	_	9	Α
T _{stg}	storage temperature	-65	+150	°C
Tj	junction temperature	_	200	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-h}	thermal resistance from junction to heatsink	T _h = 25 °C, note 1	1.15	K/W

Note

1. Determined under specified RF operating conditions.

CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{(BR)DSS}	drain-source breakdown voltage	V _{GS} = 0; I _D = 1.4 mA	65	_	_	V
V_{GSth}	gate-source threshold voltage	V _{DS} = 10 V; I _D = 140 mA	4.4	_	5.5	V
I _{DSS}	drain-source leakage current	V _{GS} = 0; V _{DS} = 26 V	_	_	10	μΑ
I _{DSX}	on-state drain current	$V_{GS} = V_{GSth} + 9 \text{ V}; V_{DS} = 10 \text{ V}$	18	_	_	А
I _{GSS}	gate leakage current	$V_{GS} = \pm 15 \text{ V}; V_{DS} = 0$	_	_	25	nA
9 _{fs}	forward transconductance	V _{DS} = 10 V; I _D = 5 A	-	4.2	_	S
R _{DSon}	drain-source on-state resistance	$V_{GS} = V_{GSth} + 9 \text{ V}; I_D = 5 \text{ A}$	_	0.15	_	Ω
C _{rss}	feedback capacitance	V _{GS} = 0; V _{DS} = 26 V; f = 1 MHz	_	3.4	_	pF

APPLICATION INFORMATION

RF performance in a common source class-AB circuit. $T_h = 25$ °C; $R_{th j-h} = 1.15$ K/W, unless otherwise specified.

MODE OF OPERATION	f	V _{DS}	I _{DQ}	P _L	G _p	η _D	d _{im}
	(MHz)	(V)	(mA)	(W)	(dB)	(%)	(dBc)
2-tone, class-AB	$f_1 = 2000; f_2 = 2000.1$	26	500	65 (PEP)	>11	>30	≤–25

Ruggedness in class-AB operation

The BLF1820-70 is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions: $V_{DS} = 26 \text{ V}$; $I_{DQ} = 500 \text{ mA}$; $P_L = 65 \text{ W}$; f = 2000 MHz.

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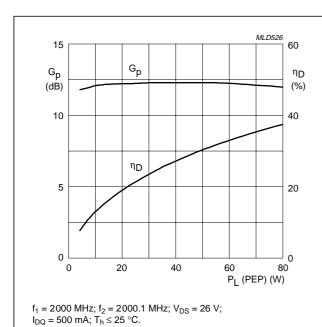


Fig.2 Power gain and drain efficiency as a function of peak envelope load power; typical values.

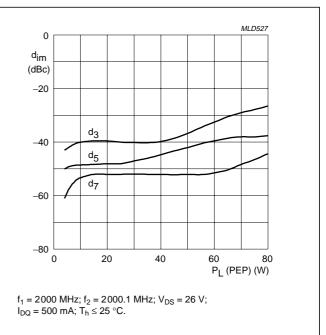
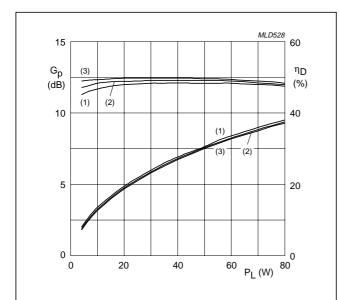


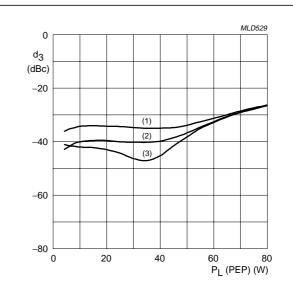
Fig.3 Intermodulation distortion as a function of peak envelope load power; typical values.



 f_1 = 2000 MHz; f_2 = 2000.1 MHz; V_{DS} = 26 V; $T_h \leq$ 25 °C.

- (1) $I_{DQ} = 400 \text{ mA}.$
- (2) $I_{DQ} = 500 \text{ mA}.$
- (3) $I_{DQ} = 600 \text{ mA}.$

Fig.4 Power gain and drain efficiency as a function of the peak envelope load power; typical values.



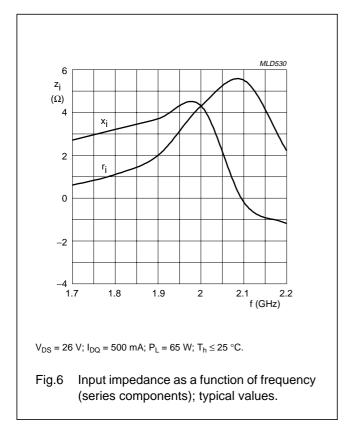
 V_{DS} = 26 V; $T_h \leq$ 25 °C; f_1 = 2000 MHz; f_2 = 2000.1 MHz.

- (1) $I_{DQ} = 400 \text{ mA}.$
- (2) $I_{DQ} = 500 \text{ mA}.$
- (3) $I_{DQ} = 600 \text{ mA}.$

Fig.5 Third order intermodulation distortion as a function of peak envelope load power; typical values.

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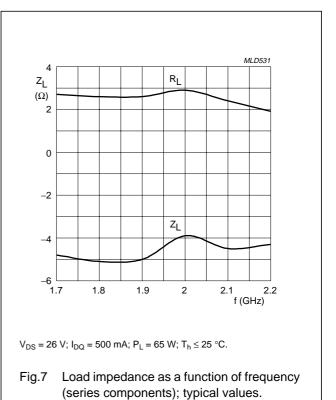


Fig.8 Class-AB test circuit at f = 2 GHz.

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List of components (see Figs. 8 and 9)

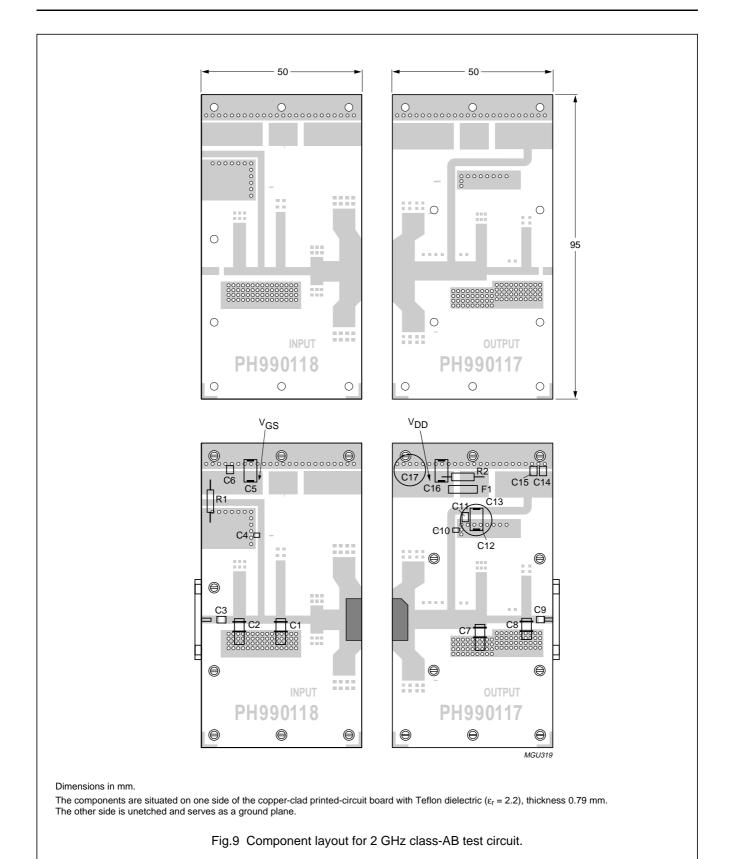
COMPONENT	DESCRIPTION	VALUE	DIMENSIONS	CATALOGUE NO.
C1, C2, C7 and C8	Tekelec variable capacitor; type 37271	0.6 to 4.5 pF		
C3, C9	multilayer ceramic chip capacitor; note 1	12 pF		
C4, C10	multilayer ceramic chip capacitor; note 2	12 pF		
C5, C12 and C16	electrolytic capacitor	4.5 μF; 50 V		
C6, C11 and C15	multilayer ceramic chip capacitor; note 1	1 nF		
C13 and C17	electrolytic capacitor	100 μF; 63 V		2222 037 58101
C14	multilayer ceramic chip capacitor	100 nF		2222 581 16641
F1	Ferroxcube chip-bead 8DS3/3/8/9-4S2			4330 030 36301
L1		50 Ω	2.9 × 2.4 mm	
L2		10.8 Ω	4 × 16.3 mm	
L3		50 Ω	3.7 × 2.4 mm	
L4		6 Ω	2 × 30.8 mm	
L5		50 Ω	3.6 × 2.4 mm	
L6		9 Ω	3 × 19.9 mm	
L7		50 Ω	7.8 × 2.4 mm	
L8		18.5 Ω	4 × 8.8 mm	
L9		24.4 Ω	5 × 6.3 mm	
L10 and L11	stripline; note 3	5.1 Ω	7 × 37 mm	
L12		25.4 Ω	10.1 × 6 mm	
L13		5.7 Ω	2.4 × 32.8 mm	
L14		25.4 Ω	6.4 × 6 mm	
L15		10 Ω	3.5 × 17.8 mm	
L16		50 Ω	10.8 × 2.4 mm	
L17		11.8 Ω	3 × 14.9 mm	
L18		50 Ω	2.3 × 2.4 mm	
L19		50 Ω	3 × 2.4 mm	
L20		50 Ω	5.5 × 2.4 mm	
R1 and R2	metal film resistor	10 Ω, 0.6 W		2322 156 11009

Notes

- 1. American Technical Ceramics type 100B or capacitor of same quality.
- 2. American Technical Ceramics type 100A or capacitor of same quality.
- 3. The striplines are on a double copper-clad printed-circuit board with Teflon dielectric (ε_r = 2.2); thickness 0.79 mm.

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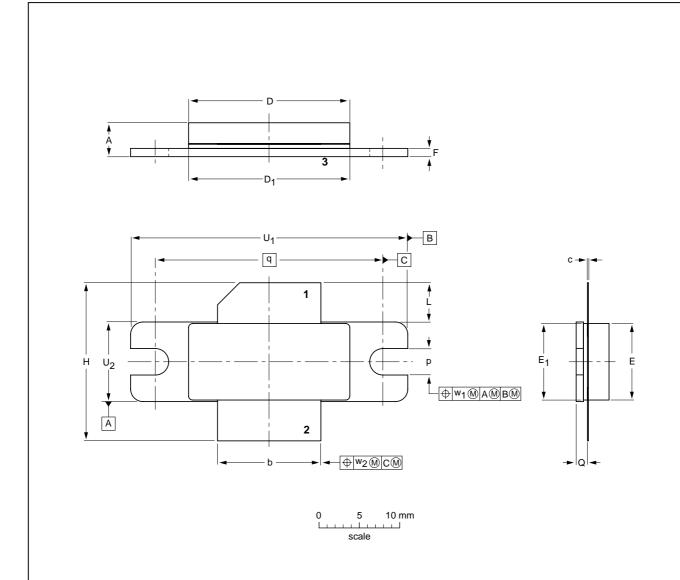
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PACKAGE OUTLINE

Flanged LDMOST ceramic package; 2 mounting holes; 2 leads

SOT502A



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	b	С	D	D ₁	E	E ₁	F	н	L	р	Q	q	U ₁	U ₂	w ₁	w ₂
mm	4.72 3.43	12.83 12.57	0.15 0.08	20.02 19.61			9.53 9.25	1.14 0.89	19.94 18.92	5.33 4.32	3.38 3.12	1.70 1.45	27.94	34.16 33.91	9.91 9.65	0.25	0.51
inches	0.186 0.135										0.133 0.123		1.100	1.345 1.335	0.390 0.380	0.01	0.02

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT502A						-99-12-28- 03-01-10

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
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NOTES

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NOTES

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Contact information

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